

MANUFACTURING METHODS OF WAFER AND CHIPS AND POSITION

ADJUSTMENT METHOD OF LASER BEAM

ABSTRACT OF THE DISCLOSURE

There is provided a manufacturing method of a wafer. The manufacturing method of a wafer includes a preparation step of preparing a wafer that includes a substrate and a stacked body disposed on the front surface side of the substrate and that has a device region and an outer circumferential surplus region, the device region having a plurality of devices disposed in a plurality of regions marked out by a plurality of planned dividing lines arranged to intersect each other, the outer circumferential surplus region surrounding the device region, and a laser processed groove forming step of forming laser processed grooves along the planned dividing lines through executing irradiation with a first laser beam with a wavelength having absorbability with respect to the stacked body, along the planned dividing lines from the side of the stacked body of the wafer.

[Fig. 1A]